L Number	Hits	Search Text	DB	Time stamp
12	3186	(polyimide near (substrate or film or tape)) and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:20
13	65	((polyimide near (substrate or film or tape)) and carrier) and ((cavity or recess or groove or trench) near (polyimide or substrate or film or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:51
14	38	(((polyimide near (substrate or film or tape)) and carrier) and ((cavity or recess or groove or trench) near (polyimide or substrate or film or tape))) and (@ad<19990903)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:55
15	1194	((polyimide or polymide) with (cavity or recess or groove or trench))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:53
16	166	(((polyimide or polymide) with (cavity or recess or groove or trench))) and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:55
17	126	((((polyimide or polymide) with (cavity or recess or groove or trench))) and carrier) and (@ad<19990903)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 12:55